

# LAMP0504MF

Rev.F Mar.-2016

## 描述 / Descriptions

SOT23-6 塑封封装低电容 TVS 二极管。

Low Capacitance TVS Array in a SOT23-6 Plastic Package.

## 特征 / Features

小封装节省空间，I/O 四端口和电源线的保护，低电容高速接口，低漏电流和低钳位电压，低工作电压。

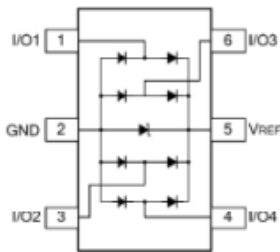
Small package saves board space , Protects up to four I/O lines & power line , Low capacitance for high-speed interfaces , Low leakage current and clamping voltage , Low operating voltage.

## 用途 / Applications

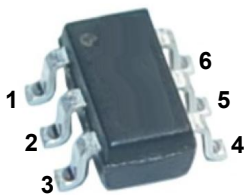
用于显示器和平板显示设备 USB2.0 高速数据保护，IEC 61000-4-2 ESD 标准：±15kV (空气环境),±8kV (接触模式)。

Transient protection for high-speed data lines to IEC 61000-4-2 (ESD) ±15kV (air),±8kV (contact) for USB 2.0,Monitors and Flat Panel Displays.

## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



## 印章代码 / Marking

Marking	24B*
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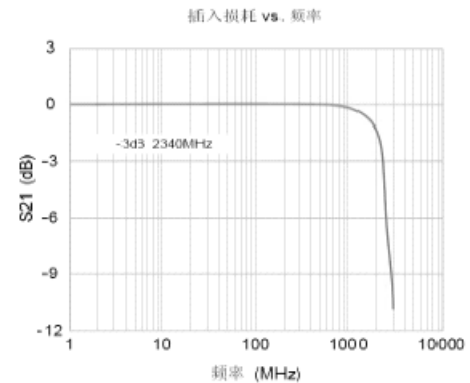
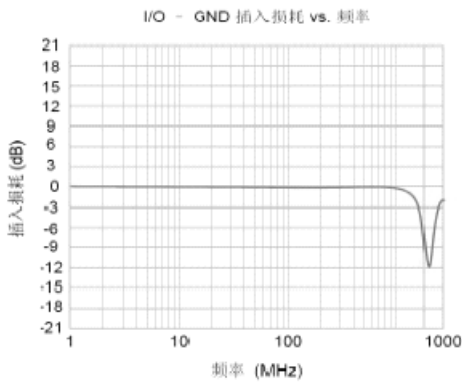
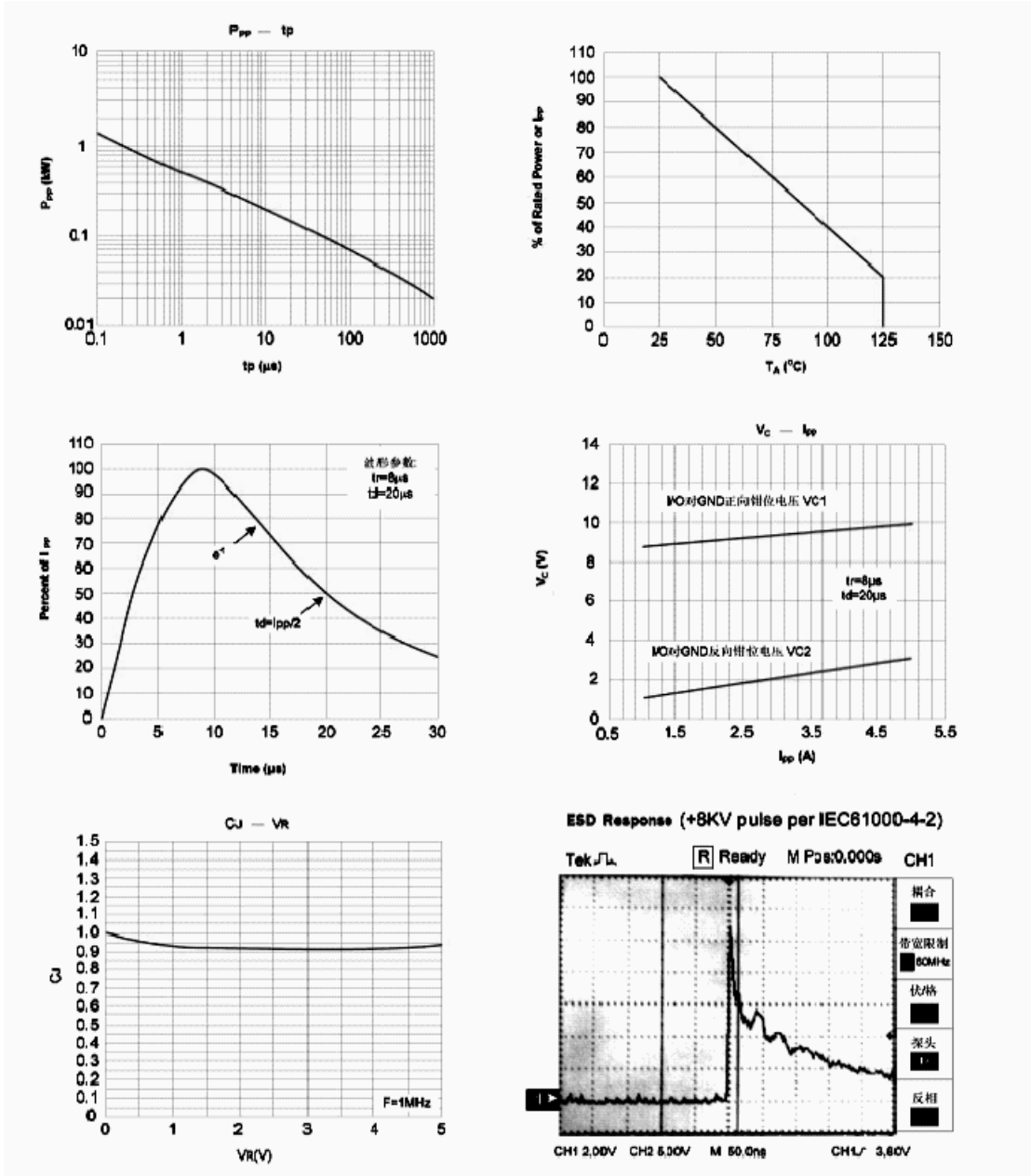
**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Peak Pulse Power (tp = 8/20μs)	PPP	150	W
Peak Pulse Current (tp = 8/20μs)	IPP	6	A
ESD per IEC 61000-4-2 (Air)	VESD 1 IEC 61000-4-2 (Air)	±15	kV
ESD per IEC 61000-4-2 (Contact)	VESD 2 IEC 61000-4-2 (Contact)	±8	kV
Operating Temperature	TOPR	-55 to 125	°C
Storage Temperature	TSTG	-55 to 150	°C

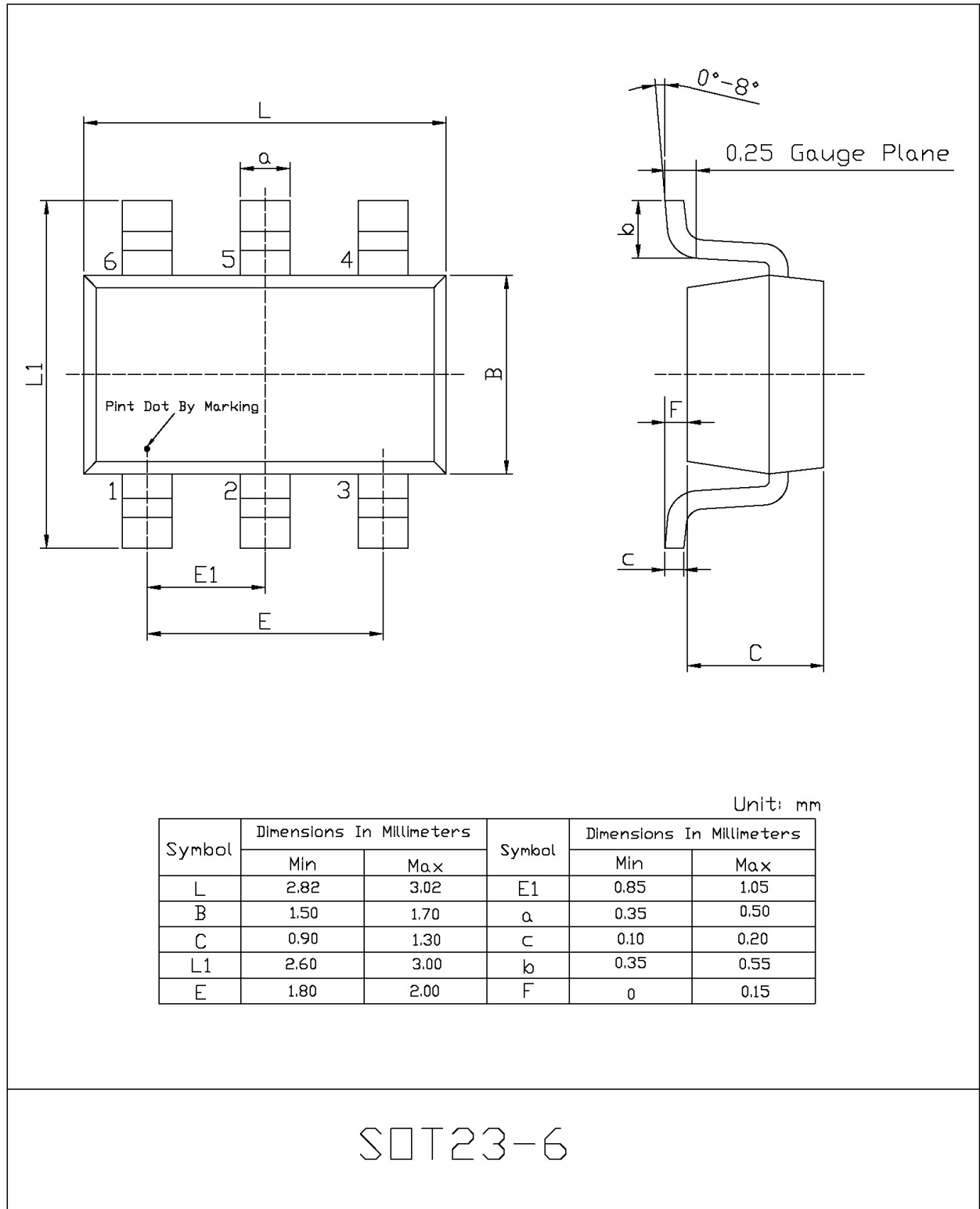
**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Reverse Stand-Off Voltage	V <sub>RWM</sub>	Pin 5 to GND			5	V
Reverse Breakdown Voltage	V <sub>BR</sub>	Pin 5 to GND I <sub>t</sub> =1mA	6			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> =5V T=25°C Pin 5 to GND			2	μA
Clamping Voltage	V <sub>C</sub>	I <sub>PP</sub> =1A tp=8/20μs Any I/O pin to GND		8.5	12	V
Junction Capacitance	C <sub>J1</sub>	V <sub>R</sub> =0V f=1MHz, Any I/O pin to GND			3	pF
Junction Capacitance	C <sub>J2</sub>	V <sub>R</sub> =0V f=1MHz Between I/O pins			1.5	pF

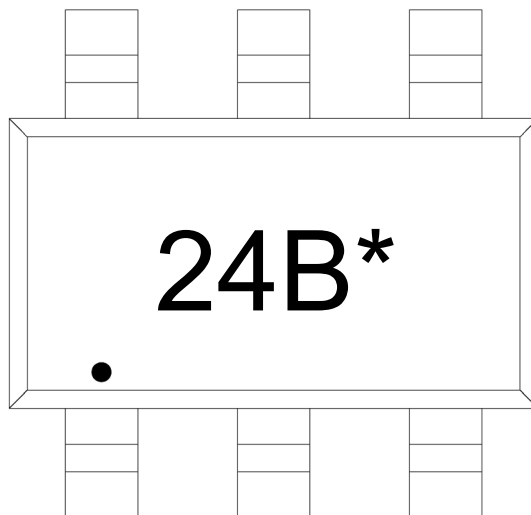
## 电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions



## 印章说明 / Marking Instructions



说明：

24B： 为型号代码

\*： 为生产批号代码，随生产批号变化。

Note:

24B: Product Type Code

\*: Lot No. Code, code change with Lot No.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT23-5/6	3,000	10	30,000	4	120,000	7" x8	210×205×205	445×230×435

**使用说明 / Notices**